

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L7	8	("5731046"   "6067368"   "6578436"   "6579833").PN. OR ("6960790").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/17 05:51
L20	8	("5679833"   "5731046"   "5828773"   "5862248"   "6067368"   "6578436"   "6579833"   "6960790").PN. OR ("7235853").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/17 06:10
L21	2	("6759745").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/11/17 06:28
L22	5	@ad<="20021209" and encapsulat\$3 same ("fingerprint sensor" or "touch sensor") with thick\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/17 06:59
L23	2	@ad<="20021209" and ("fingerprint sensor" or "touch sensor") with (chip or "IC" or die) with thick\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/17 07:00
L24	57	@ad<="20021209" and packag\$3 with thickness same (sensitive or sensor or touch) with (chip or "IC" or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/17 07:01
L25	2	@ad<="20021209" and packag\$3 with thickness with "inch" same (sensitive or sensor or touch) with (chip or "IC" or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/17 07:04
L26	862	@ad<="20021209" and packag\$3 with thickness with "inch"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/17 07:04
L27	37	@ad<="20021209" and package with thickness with "inch" same die	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/17 07:05
S1	2	"20040056338"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:03
S2	3	"6639308"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 09:40

S3	1	"6388336".PN.	USPAT	OR	OFF	2004/10/06 09:45
S4	2809	@ad<="19991216" and (257/666).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:21
S5	238	@ad<="19991216" and (257/672).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:21
S6	1553	@ad<="19991216" and (257/676).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S7	673	@ad<="19991216" and (257/e23.039).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S8	1127	@ad<="19991216" and (257/692).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S9	200	@ad<="19991216" and (438/111).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:06
S10	570	@ad<="19991216" and (438/123).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:06
S11	348	@ad<="19991216" and (257/670).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S12	571	@ad<="19991216" and (257/677).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S13	99	@ad<="19991216" and (257/e23.141).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:10
S14	915	@ad<="19991216" and (257/e23.043).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:11
S15	52	@ad<="19991216" and (257/e23.045).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:11

S16	24	@ad<="19991216" and (257/e23.05).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:11
S17	330	@ad<="19991216" and (257/e23.052).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:12
S18	303	@ad<="19991216" and (257/e23.066).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:12
S19	83	@ad<="19991216" and (257/666).ccls. and 'lead frame' and 'notch'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:13
S20	559	@ad<="19991216" and (361/813).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:21
S21	76	@ad<="19991216" and 'lead frame' and 'tie bar' and 'notch'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 10:58
S22	2	@ad<="19991216" and 'chip' same 'lead frame' and 'various' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:01
S23	2	("6239487").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/10/06 11:00
S24	2	@ad<="19991216" and 'lead frame' and 'various' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:37
S25	164	@ad<="19991216" and 'lead frame' and 'different' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38
S26	57	@ad<="19991216" and 'lead frame' same 'different' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38
S27	37	@ad<="19991216" and 'semiconductor package' and 'lead frame' and 'different' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 08:58

S28	23	@ad<="19991216" and 'lead frame' same 'variable' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38
S29	108	@ad<="19991216" and 'lead frame' with 'flange'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38
S30	120	@ad<="19991216" and 'semiconductor package' and 'leadframe' with 'step'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:29
S31	1	@ad<="19991216" and 'leadframe' and 'various' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:37
S32	31	@ad<="19991216" and 'leadframe' and 'different' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38
S33	11	@ad<="19991216" and 'leadframe' same 'different' with 'chip' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38
S34	5	@ad<="19991216" and 'leadframe' same 'variable' with 'size'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/10/06 11:38
S35	11	@ad<="19991216" and 'leadframe' with 'flange'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 09:45
S70	2811	@ad<="19991216" and (257/666).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:21
S71	238	@ad<="19991216" and (257/672).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:21
S72	1554	@ad<="19991216" and (257/676).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S73	674	@ad<="19991216" and (257/e23.039).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S74	1128	@ad<="19991216" and (257/692).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22

S75	349	@ad<="19991216" and (257/670).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S76	571	@ad<="19991216" and (257/677).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/05 09:22
S94	2	@ad<="20001013" and 'lead-on-chip' and 'tiebar'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 09:22
S101	1	'5357139'.PN.	USPAT; USOCR	OR	ON	2005/01/05 12:16
S102	44	@ad<="20001013" and 'lead-on-chip' and 'tie bar'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 09:22
S107	782	@ad<="19991216" and 'lead frame' and 'tie bar' and 'die'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 09:46
S108	10	@ad<="19991216" and 'lead frame' and 'tie bar' and 'die' and 'sealing material'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 10:06
S110	66	@ad<="19991216" and 'lead frame' and 'tie bar' and 'LOC'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 10:01
S111	11	@ad<="19991216" and 'lead frame' and 'tie bar' and 'COL'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 10:01
S112	240	@ad<="19991216" and 'lead frame' and 'tie bar' and 'die' and 'sealing'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/28 10:06
S113	19354	@ad<="20040113" and (257/690).ccls. or (257/730).ccls. or (257/787)".ccls" or (257/686).ccls. or (257/783).ccls. or (257/777).ccls. or (257/696).ccls. or (257/676).ccls. or (257/707).ccls. or (257/675).ccls. or (257/666).ccls. (257/692).ccls. or (257/711).ccls. (257/784).ccls. or (257/731).ccls. or (257/106).ccls. or (438/106).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:34

S114	6	@ad<="20040113" and 'chip' and 'tie bars' and 'chip paddle' and 'lead' and 'bonding pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:42
S115	22	@ad<="20040113" and 'chip' and 'tie bars' and 'chip pad' and 'lead' and 'bonding pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:35
S116	188	@ad<="20040113" and 'chip' and 'tie bar' and ('chip paddle' or 'die pad') and 'bonding pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 09:51
S134	45	(US-20040056338-\$).did. or (US-3902148-\$ or US-3909838-\$ or US-5065223-\$ or US-5424577-\$ or US-5559366-\$ or US-5648682-\$ or US-5763829-\$ or US-5786639-\$ or US-5818105-\$ or US-5834831-\$ or US-5894107-\$ or US-5923092-\$ or US-5929513-\$ or US-5929514-\$ or US-6002181-\$ or US-6020625-\$ or US-6040620-\$ or US-6046504-\$ or US-6081029-\$ or US-6104095-\$ or US-6157074-\$ or US-6197615-\$ or US-6198171-\$ or US-6229200-\$ or US-6239487-\$ or US-6242287-\$).did. or (US-6246113-\$ or US-6256200-\$ or US-6268646-\$ or US-6291881-\$ or US-6307755-\$ or US-6335548-\$ or US-6355502-\$ or US-6388336-\$ or US-6410979-\$ or US-6414385-\$ or US-6448633-\$ or US-6455348-\$ or US-6525406-\$ or US-6559525-\$ or US-6639308-\$ or US-6838754-\$).did. or (WO-8705153-\$ or JP-11260987-\$).did.	US-PGPUB; USPAT; DERWENT	OR	ON	2007/11/16 17:32
S142	4	((("6552419") or ("6313528")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2007/11/16 17:51
S143	55	@ad<="20021209" and ("flip-chip" or "flip chip") and ("lead frame" or leadframe) and (encapsulat\$3 or resin) and solder with "metal bump"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 17:54

S145	316	@ad<="20021209" and "BGA" and ("flip-chip" or "flip chip") same ("lead frame" or leadframe)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 17:59
S146	296	@ad<="20021209" and "BGA" and ("flip-chip" or "flip chip") same ("lead frame" or leadframe) and solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 18:00
S147	62	["5492266"   "5535936"   "5542601"   "5849608"   "6297142"   "6337522").PN. OR ("6482680").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/16 18:06
S148	7	["20020031902"   "20040169275"   "6482680"   "6507120"   "6577012"   "6597059"   "6661087").PN. OR ("7169641").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/16 18:08
S149	655	@ad<="20021209" and ("flip-chip" or "flip chip") with ("lead frame" or leadframe)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 18:44
S150	513	@ad<="20021209" and "flip chip" with "lead frame"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 18:50
S151	307	@ad<="20021209" and "flip chip" with "lead frame" and solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 18:51
S152	22	["3670396"   "4010885"   "4605833"   "4867715"   "5252853"   "5463245"   "5789803"   "5946590"   "6008532"   "6150724"   "6172419"   "6214642"   "6225144"   "6258622"   "6348399"   "6350668"   "6369448"   "6376352"   "6408510"   "6410415"   "6441488").PN. OR ("6828220").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/16 18:53
S153	812	@ad<="20021209" and "lead-on-chip"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:03
S154	115	@ad<="20021209" and "lead-on-chip" same encapsulat\$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:03

S155	29	@ad<="20021209" and "lead-on-chip" same encapsulant	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:04
S156	1	@ad<="20021209" and "lead-on-chip" same sensor with chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:04
S157	4	@ad<="20021209" and "lead-on-chip" and sensor with chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:04
S158	369	@ad<="20021209" and ("flip-chip" or "flip chip") same ("lead frame" or leadframe) and expose\$3 with (chip or "IC" or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:06
S159	233	@ad<="20021209" and ("flip-chip" or "flip chip") same ("lead frame" or leadframe) and expose\$3 with (chip or "IC" or die) with surface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:07
S160	47	@ad<="20021209" and ("flip-chip" or "flip chip") same ("lead frame" or leadframe) and expose\$3 with (chip or "IC" or die) same step\$3 with surface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:07
S161	458	@ad<="20021209" and ("lead frame" or leadframe) and expose\$3 with (chip or "IC" or die) same step\$3 with surface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:14
S162	326	@ad<="20021209" and ("lead frame" or leadframe) and expose\$3 with (chip or "IC" or die) with step\$3 with surface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:15
S163	130	["3833984"   "3851221"   "4530152"   "4567643"   "4707724"   "4730232"   "4756080"   "4763188"   "4812896"   "4982265"   "4996587"   "5012323"   "5025306"   "5040052"   "5041902"   "5138438"   "5140404"   "5157480"   "5165067"   "5172213"   "5172214"   "5198888"   "5200362"   "5200809"   "5214845"   "5216278"   "5221642"   "5229647"   "5258094"   "5273938"	US-PGPUB; USPAT; USOCR	OR	ON	2007/11/16 21:17



		"5277972"   "5278446"   "5279029"   "5291061"   "5323060"   "5332864"   "5334875"   "5336931"   "5343076"   "5347429"   "5406124"   "5422435"   "5424576"   "5426563"   "5432729"   "5435057"   "5463253"   "5473196"   "5495394"   "5495398"   "5502289"   "5514907"   "5521429"   "5569625"   "5581498"   "5587341"   "5604376"   "5608267"   "5614766"   "5637536"   "5637912"   "5639990"   "5640047"   "5641997"   "5646831"   "5650663"   "5682062"   "5683806"   "5689135"   "5696031"   "5696666"   "5701034"   "5710064"   "5715147"   "5721452"   "5736432"   "5739581"   "5776798"   "5783861"   "5783870"   "5793108"   "5798014"   "5815372"   "5835988"   "5859471"   "5861666"   "5866939"   "5872025"   "5877043"   "5885849"   "5886412"   "5894108"   "5917242"   "5952611"   "5973403"   "5977613"   "5977630"   "5981314"   "6001671"   "6005778"   "6025640"   "6051886"   "6057598"   "6072243"   "6080264"   "6130115"   "6130473"   "6133637"   "6143981"   "6184463"   "6198171"   "6214641"   "6225146"   "6229200"   "6235554"   "6242281"   "6281568"   "6326696"   "6414385"   "6476474"   "6559525"   "RE36613"). PN. OR ("6759737").URPN.				
S164	787	@ad<="20021209" and ("lead frame" or leadframe) same (chip or "IC" or die) with step\$3 with surface	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:19
S165	45	@ad<="20021209" and packag\$3 same stimulus with (chip or "IC" or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:22

S166	268	@ad<="20021209" and packag\$3 same touch with (chip or "IC" or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:24
S167	2	@ad<="20021209" and packag\$3 same touch with sensitive with (chip or "IC" or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:24
S168	912	@ad<="20021209" and packag\$3 same sensitive with (chip or "IC" or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:25
S169	699	@ad<="20021209" and touch with surface with (chip or "IC" or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:29
S170	276	@ad<="20021209" and ("fingerprint sensor" or "touch sensor") with (chip or "IC" or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:33
S172	14	@ad<="20021209" and encapsulat\$3 same ("fingerprint sensor" or "touch sensor") with (chip or "IC" or die)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/11/16 21:33

11/17/07 10:34:43 AM

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Ball, Bonding Pad, Testing\10536859 Advance Interconnect lead frame 257.wsp